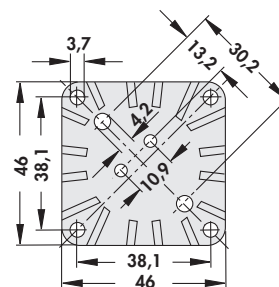
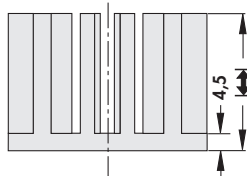
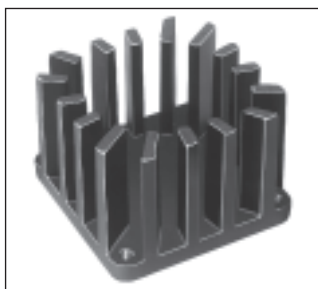


Fingerkühlkörper für Leistungshalbleiter

Finger-Shaped heatsinks for power semiconductors

Dissipateurs à doigts pour semi-conducteurs de puissance



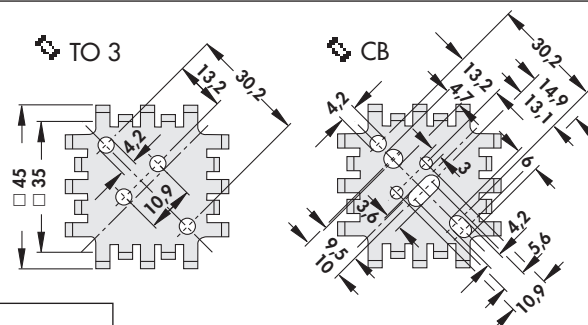
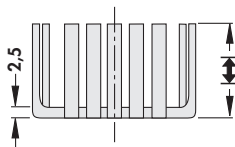
TO 3

Art. Nr. Art. No. Art. n°		Art. Nr. Art. No. Art. n°		↔ [mm]	R _w [K/W]
FK 318 SA	ohne without sans	FK 318 SA-3	TO 3	31,8	4,8
FK 254 SA		FK 254 SA-3		25,4	5,8
FK 191 SA		FK 191 SA-3		19,1	6,6
FK 127 SA		FK 127 SA-3		12,7	8,0

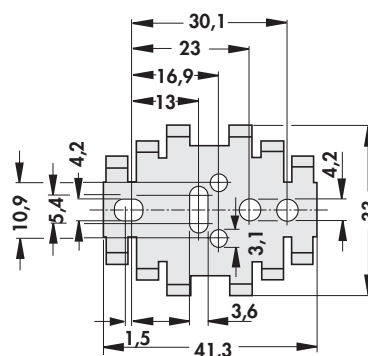
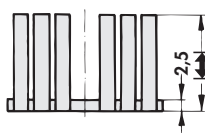
Material: Aluminium Druckguß
Oberfläche: schwarz lackiert

Material: Die-Cast Aluminium
Surface: black lacquered

Matière: Aluminium moulé sous pression
Surface: peinte noire



Art. Nr. Art. No. Art. n°	R _w [K/W]	↔ [mm]	Art. Nr. Art. No. Art. n°	R _w [K/W]	↔ [mm]	
FK 201 SA	6	25,4	FK 202 SA	8	12,7	ohne/without/sans
FK 201 SA 3			FK 202 SA 3			TO 3
FK 201 SA CB			FK 202 SA CB			CB



L = (TO 3 – SOT 9 + TO 66 – SOT 32 – TO 220)

Art. Nr. Art. No. Art. n°	R _w [K/W]	↔ [mm]
FK 205 SA L	9,0	31,8
FK 206 SA L	10,5	25,4
FK 207 SA L	12,0	19,1
FK 208 SA L	14,0	12,7

Material: Aluminium
Oberfläche: schwarz eloxiert

Material: Aluminium
Surface: black anodised

Matière: Aluminium
Surface: anodisée noire